

Crystal LTD TM SPEC Form

Customer

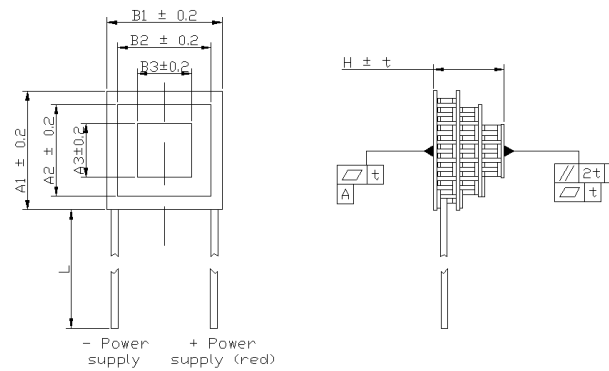
PO#

PO date

Thermoelectric module (TM) specification

PO position #	TM	Internal Solder Melting Temp, C	Max operating temperature, °C		Parameters in vacuum at hot side temperature 25 °C				Rac at 25 °C		Ceramic size, mm		TM Height		Wire			Sealing
			short time	long time	I _{max} , A	U _{max} , V	Q _{max} , W	dT _{max} , K	Rac, Ohm	Tolerance ±, %	A1/A2/A3	B1/B2/B3	Height, mm	Tolerance t, ± mm	S, AWG #	Length, mm	Tolerance ±, mm	
1	3-229-20-15-L2	138	130	115	9.6	17.0	26.5	119	1.81	10	62/40/31	62/40/31	12.90	0.02	20	100	5	

Clamping force: 11.2 - 22.4 kg



Max dT is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.

Q(dT) at $T_{hot}=298K$

